

STRUCTURE	Silicon Monolithic Integrated Circuit
PRODUCT SERIES	2-Phase Half-Wave Pre Driver for Fan Motor
TYPE	B A 6 9 0 1 F
FEATURES	Current limit circuit PWM control (PWM pulse signal input) Charge - discharge pulse circuit

○ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Limit	Unit
Supply Voltage	Vcc	36	V
Power dissipation	Pd	625 *	mW
Operating temperature range	Topr	-40~+100	°C
Storage temperature range	Tstg	-55~+150	°C
Output current	Iomax	70	mA
FG Signal output current	IFG	15	mA
FG Signal output voltage	VFG	36	V
AL Signal output current	IAL	15	mA
AL Signal output voltage	VAL	36	V
Junction temperature	Tjmax	150	°C

* To use at temperature above Ta=25°C reduce 5.0mW/°C.
(On 70.0mm × 70.0mm × 1.6mm glass epoxy board)

○OPERATING CONDITIONS

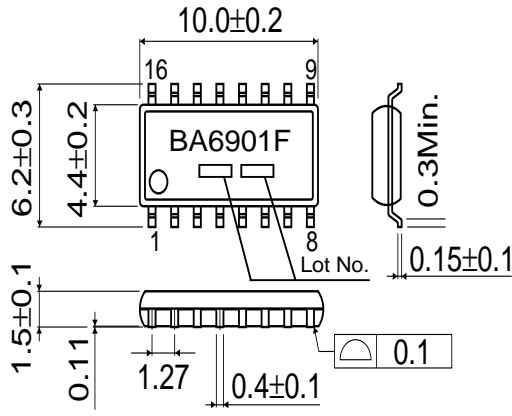
Parameter	Symbol	Limit	Unit
Operating supply voltage range	Vcc	3.5~28.0	V
Hall input voltage range	VH	0~Vcc-2.2	V

* This product is not designed for production against radioactive rays.
* This document may be strategic data subject to COCOM regulations.

ELECTRICAL CHARACTERISTICS (Unless otherwise specified Ta=25°C, Vcc=12V)

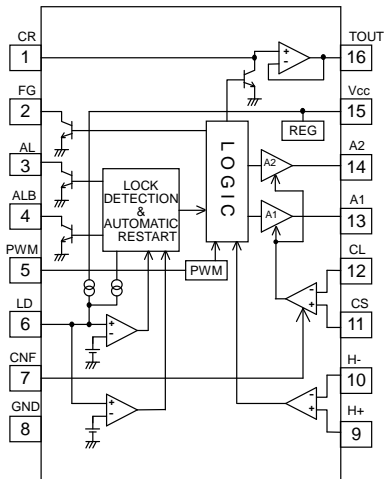
Parameter	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Circuit current	Icc	3.0	7.0	12.0	mA	At output OFF
Hall input hysteresis	Vhys	±4	±10	±20	mV	
Charge current of capacitor for lock detection	ILDC	2.0	5.0	8.0	μA	VLD=1.5V
Discharge current of capacitor for lock detection	ILDD	0.2	0.5	0.8	μA	VLD=1.5V
Charge-discharge current ratio of capacitor for lock detection	rCD	4	10	16	-	rCD=ILDC/ILDD
Clamp voltage of capacitor for lock detection	VLDCL	1.60	2.40	3.20	V	
Comparison voltage of capacitor for lock detection	VLDCP	0.25	0.60	0.95	V	
Output H voltage	VOH	-	1.5	2.0	V	Io=-10mA Voltage between output and Vcc
Hall signal output L voltage	VFG	-	0.10	0.50	V	IFG=5mA
Alarm output L voltage	VAL	-	0.10	0.50	V	IAL,IALB=5mA
CL-CS offset voltage	VofsCS	75.0	92.0	99.5	mV	CL=100mV
Response time for current limit	TCS	-	50	150	μsec	
PWM input voltage H	VPWMH	2.0	-	-	V	At output ON
PWM input voltage L	VPWML	-	-	0.8	V	At output OFF
Charge-discharge pulse comparison voltage	VCRCP	0.26	0.35	0.44	V	
Charge-discharge pulse output voltage H	VTOH	0.7	1.0	1.3	V	ITO=-0.5mA Voltage between output and Vcc
Charge-discharge pulse output voltage L	VTOL	0.7	1.0	1.3	V	ITO=0.5mA

PACKAGE OUTLINES



SOP16 (UNIT:mm)

BLOCK DIAGRAM



Terminal name

Pin No.	Terminal name
1	CR
2	FG
3	AL
4	ALB
5	PWM
6	LD
7	CNF
8	GND
9	H+
10	H-
11	CS
12	CL
13	A1
14	A2
15	Vcc
16	TOUT

OCAUTIONS

- 1) Absolute maximum ratings
There is possibility of destruction in using beyond the absolute maximum rating. In case of destruction, a failure mode can not be defined (short mode or open mode). Therefore when special mode is envisaged where absolute maximum rating may be exceeded, please take a physical safety measure such as fuse.
- 2) Reverse connection of power supply connector
Reverse connection of power supply connector may break IC. Take a measure against reverse connection destruction such as inserting a diode between power supply and Vcc terminal.
- 3) Power supply line
Back electromotive force causes regenerated current to power supply line, therefore take a measure such as placing a capacitor between power supply and GND for routing regenerated current, and fully ensure that the capacitor characteristics have no problem before determine a capacitor value
- 4) GND potential
Ensure that the potential of GND terminal is the minimum potential in any operating condition. Also ensure that all terminals except GND terminal do not fall below GND voltage including transient characteristics. However, it is possible that the motor output terminal may deflect below GND because of influence by back electromotive force of motor. Malfunction may possibly occur depending on use condition, environment, and property of individual motor. Please make fully confirmation that no problem is found on operation of IC.
- 5) Thermal design
Consider the power dissipation under actual use condition and apply thermal design with sufficient margin.
- 6) Mounting failures
In attaching IC to printed board, pay enough attention to the direction and dislocation of IC. Mounting failures may break IC. In addition, destruction is also possible when circuit is shorted by foreign substance brought between outputs or between output and power supply - GND.
- 7) Operation in strong electromagnetic field
Use in strong electromagnetic field may cause malfunction, please be careful.
- 8) ASO
Please consider that the output Tr does not exceed the absolute maximum rating and ASO.
- 9) Thermal shut down circuit
This IC has thermal shut down (TSD) circuit. Operation temperature is 175°C(typ.) and has a hysteresis width of 25°C(typ.). When IC chip temperature rises and TSD circuit works, the output terminal becomes an open state. TSD circuit is simply for the purpose of intercepting IC from overheating, and not for protecting and assuring IC. Therefore do not continue to use IC thereafter with this circuit operating and do not use IC assuming the operation of this circuit.
- 10) Inspection with a set board
When connecting a capacitor to a pin with low impedance in inspection on a set board, stress may possibly be applied to IC, therefore be sure to apply discharging in each process. In attaching to and detaching from jigs in inspection process, be sure to turn off power before connecting, and turn off power before removing IC. In addition, apply grounding to assembling process as a measure of anti-static electricity, and use full caution in transporting and storing.
- 11) GND wiring pattern
When there are small signal GND and large current GND, separate the large current GND pattern from small signal GND pattern. It is recommended to apply one-point grounding at the reference point of the set in order that resistance of wiring pattern and large current do not cause change of voltage of small signal GND. Please be cautious not to fluctuate the wiring pattern of GND of external mounted parts.
- 12) Capacitor between output and GND
When a large capacitor is connected between output and GND, if Vcc is shorted with 0V or GND for some cause, it is possible that the current charged in the capacitor may flow into the output resulting in destruction. Keep the capacitor between output and GND below 100uF.
- 13) IC terminal input
When Vcc voltage is not applied to IC, do not apply voltage to each input terminal. When voltage above Vcc or below GND is applied to the input terminal, parasitic element is actuated due to the structure of IC. Operation of parasitic element causes mutual interference between circuits, resulting in malfunction as well as destruction in the last. Do not use in a manner where parasitic element is actuated.

Notes

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